WEST Search History

DATE: Thursday, May 15, 2003

Set Name Query side by side			Set Name result set				
DB=USPT,PGPB; PLUR=YES; OP=ADJ							
. L9	12 near7 (13 or 14 or 15 or 16)	77	L9				
L8	12 near7 (13 or 14 or 15 or 16)	77	L8				
DB=JB	PAB,EPAB,DWPI,TDBD; PLUR=YES; OP=ADJ						
L.7	(thiirane or episulfide or episulphide or epithio\$ or dithiirane or polythiirane or diepisulfide or diepisulphide or polyepisulfide or polyepisulphide or diepithio\$ or polyepithio\$) and ((amin?\$1 or diamin?\$1 or polyamin?\$! or butylamine or octylamine or cyclohexylamine or benzylamine or methylbutylamine) or (diaminopropane or propanediamine or propylenediamine or diaminocyclohexane or cyclohexanediamine or aminoethylpiperazine or (aminoethyl adj piperazine)) or (diethylenetriamine or triamine or isophoronediamine or xylylenediamine or (diamin? adj3 methylpentane) or methylpentanediamine) or (aminomethylnorbornane or (aminomethyl adj norbornane) or ethylenediamine))	144	L7				
<i>DB=U</i> L6	aminomethylnorbornane or (aminomethyl adj	40569	L6				
L5	norbornane) or ethylenediamine diethylenetriamine or triamine or isophoronediamine or xylylenediamine or (diamin? adj3 methylpentane) or methylpentanediamine	25588	L5				
L4	diaminopropane or propanediamine or propylenediamine or diaminocyclohexane or cyclohexanediamine or aminoethylpiperazine or (aminoethyl adj piperazine)	15591	L4				
L3	amin?\$1 or diamin?\$1 or polyamin?\$! or butylamine or octylamine or cyclohexylamine or benzylamine or methylbutylamine	392132	L3				
L2	thiirane or episulfide or episulphide or epithio\$ or dithiirane or polythiirane or diepisulfide or diepisulphide or polyepisulfide or polyepisulphide or diepithio\$ or polyepithio\$	1013	L2				

DB=DWPI; PLUR=YES; OP=ADJ
L1 ep-449776-\$.did.

1 L1

END OF SEARCH HISTORY

End of Result Set

Generate Collection Print

L1: Entry 1 of 1

File: DWPI

Sep 3, 2002

DERWENT-ACC-NO: 1991-290167

DERWENT-WEEK: 200266

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TITLE: Epoxy! resin with improved fracture toughness - contg. epoxy! resin, anhydride hardener, impact modifier and a cpd. with

2 active hydrogen atoms

INVENTOR: ELDIN, S H; MAURER, J; PEYER, R P; GRIESHABER, P; RIME, F

PATENT-ASSIGNEE:

ASSIGNEE CODE
CIBA GEIGY AG CIBA
VANTICO AG VANTN
CIBA SC HOLDING AG CIBA
CIBA SPECIALTY CHEM HOLDING INC CIBA
CIBA SPECIALTY CHEM CORP CIBA

PRIORITY-DATA: 1990CH-0001055 (March 30, 1990)

PATENT-FAMILY: •

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
CA 2039404 C	September 3, 2002	E	000	C08L051/04
EP 449776 A	October 2, 1991		000	
AU 9173970 A	October 3, 1991		000	•
CA 2039404 A	October 1, 1991		000	
ZA 9102361 A	December 24, 1991		000	
AU 638816 B	July 8, 1993		000	C08G059/58
EP 449776 A3	September 23, 1992		000	
JP 06049179 A	February 22, 1994		012	C08G059/42
US 5789482 A	August 4, 1998		000	C08L063/00
KR 193147 B1	June 15, 1999		000	C08L063/00
JP 3300955 B2	July 8, 2002		012	C08G059/42

DESIGNATED-STATES: CH DE ES FR GB IT LI NL SE

CITED-DOCUMENTS:NoSR.Pub; EP 191872; EP 245018; US 3856883

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
CA 2039404C	March 28, 1991	1991CA-2039404	
EP 449776A	March 21, 1991	1991EP-0810191	
ZA 9102361A	March 28, 1991	1991ZA-0002361	
AU 638816B	March 28, 1991	1991AU-0073970	
AU 638816B		AU 9173970	Previous Publ.
EP 449776A3	March 21, 1991	1991EP-0810191	
JP 06049179A	March 29, 1991	1991ЈР-0091759	
US 5789482A	March 25, 1991	1991US-0674637	CIP of
US 5789482A	September 28, 1992	1992US-0952122	
KR 193147B1	March 20, 1991	1991KR-0004364	
JP 3300955B2	March 29, 1991	1991JP-0091759	
JP 3300955B2		JP 6049179	Previous Publ.

INT-CL (IPC): B32B 27/38; C08G 59/40; C08G 59/42; C08G 59/58; C08G 59/62; C08J 0/00; C08K 0/00; C08L 21/00; C08L 51/00; C08L 51/04; C08L 63/02; C08L 63/04

ABSTRACTED-PUB-NO: EP 449776A BASIC-ABSTRACT:

Epoxy resinm compsns. (I) are claimed, contg, (a) epoxy resin(s) with more than one 1,2-epoxide gp./mol. on average, (b) anhydride hardener, (c) impact modifier, and (d) a cpd. with 2 active H atoms which can react with (a).

- (I) also contain a fillers, (a) is based on Bisphenol A or F or on a cyclo-olefin, has 2 epoxide gps./mol. and is a low-viscosity liq. (b) is a linear aliphatic polymeric anhydride or (pref.) a cyclic carboxylic acid anhydride. (I) also contains an accelerator for (b).
- (c) is a core/shell polymer, pref. with no gps. in the shell which react with epoxide gps., pref. with particle size 0.05-30 microns and pref. with a core contg. polybutadiene.

USE/ADVANTAGE - (I) are useful as casting resins, laminating resins, moulding resins, coating materials or encapsulating resins for electrical or electronic components (claimed). Also claimed are cured prods. obtd. by hardening (I) by conventional methods.

ABSTRACTED-PUB-NO:

US 5789482A EQUIVALENT-ABSTRACTS:

Epoxy resinm compsns. (I) are claimed, contg, (a) epoxy resin(s) with more than one 1,2-epoxide gp./mol. on average, (b) anhydride hardener, (c) impact modifier, and (d) a cpd. with 2 active H atoms which can react with (a).

- (I) also contain a fillers, (a) is based on Bisphenol A or F or on a cyclo-olefin, has 2 epoxide gps./mol. and is a low-viscosity liq. (b) is a linear aliphatic polymeric anhydride or (pref.) a cyclic carboxylic acid anhydride. (I) also contains an accelerator for (b). (c) is a core/shell polymer, pref. with no gps. in the shell which react with epoxide gps., pref. with particle size 0.05-30 microns and pref. with a core contg. polybutadiene.
- USE/ADVANTAGE (I) are useful as casting resins, laminating resins, moulding resins, coating materials or encapsulating resins for electrical or electronic components (claimed). Also claimed are cured prods. obtd. by hardening (I) by conventional methods.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: POLYEPOXIDE RESIN IMPROVE FRACTURE TOUGH CONTAIN POLYEPOXIDE RESIN ANHYDRIDE HARDEN IMPACT MODIFIED COMPOUND ACTIVE HYDROGEN ATOM

DERWENT-CLASS: A21 A85 L03 P73 U11 V04

CPI-CODES: A05-A01B1; A08-D02; A08-M10; L03-H04E8; L03-J; L04-C20A;

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L7: Entry 111 of 144

File: DWPI

Apr 15, 1977

DERWENT-ACC-NO: 1977-38194Y

DERWENT-WEEK: 197722

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TITLE: Storable liq. episulphide resins - from mixts. of epoxy resins and thiourea in solvent soln.

PATENT-ASSIGNEE:

ASSIGNEE

CODE

SIKA AG

SIKAN

PRIORITY-DATA: 1974CH-0002455 (February 21, 1974)

PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

PAGES

MAIN-IPC

CH 586732 A

April 15, 1977

000

INT-CL (IPC): C07D 331/02; C08G 85/00; C08L 63/00; C08L 101/02

ABSTRACTED-PUB-NO: CH 586732A

BASIC-ABSTRACT:

Prepn. comprises reaction of a mixt. of epoxy resins in solvent with thiourea. Alternatively, different epoxy resins can be separately reacted and the episulphide resins obtd. can then be mixed.

Used as a component of hardenable resin compsns. partic. with <u>polyamines- and</u> as an accelerator for epoxy-polyamide resin mixts. used in the building industry. Prods. are practically odourless and have less tendency to gel than those obtd. using thiocyanates or Na thiosulphate.

In an example an <u>episulphide</u> resin prepd. from 48 g Bisphenol A type epoxy resin (epoxy value 0.56), 50 g same type of epoxy value 0.22 and 2 g of aliphatic diglycidyl ether of epoxy value 0.70 had a storage stability of 4 months at 20 degrees C and only slight odour.

TITLE-TERMS: STORAGE LIQUID $\underline{\text{EPISULPHIDE}}$ RESIN MIXTURE EPOXY RESIN THIOUREA SOLVENT SOLUTION

DERWENT-CLASS: A26

CPI-CODES: A05-A01D; A05-J05; A08-D;

Multipunch Codes: 010 02& 040 05- 141 199 220 221 226 231 250 273 299 311 336 341 359 400 475 525 527 532 536 546

613 720 724

Generate Collection

Print

L7: Entry 75 of 144

File: DWPI

Jul 11, 1995

DERWENT-ACC-NO: 1995-272961

DERWENT-WEEK: 199536

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TITLE: Mfr. of modified polyamide-poly:amine(s) with excellent curative properties - comprises reacting thiirane cpd. and polyamide-poly:amine without formation of by=product sulphur cpds.

PATENT-ASSIGNEE:

ASSIGNEE

CODE

NIPPON SHOKUBAI CO LTD

JAPC

PRIORITY-DATA: 1993JP-0317979 (December 17, 1993)

PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

PAGES

MAIN-IPC

JP 07173283 A

July 11, 1995

004

C08G073/02

APPLICATION-DATA:

PUB-NO

APPL-DATE

APPL-NO

DESCRIPTOR

JP 07173283A

December 17, 1993

1993JP-0317979

INT-CL (IPC): <u>C07 D</u> <u>331/02</u>; <u>C08 G</u> <u>69/48</u>; <u>C08 G</u> <u>73/02</u>

ABSTRACTED-PUB-NO: JP 07173283A

BASIC-ABSTRACT:

The mfr. of a modified polyamide-polyamine comprises reacting a <u>thiirane</u> cpd. of formula (I) and a polyamide-polyamine cpd. R1-4=H, alkyl or aromatic gp..

USE - Used as epoxy resin curatives, crosslinkers, vulcanisers, polymerisation regulators, antioxidants, metal-chelating agents and additives for lubricating oils.

ADVANTAGE - By-product S cpds. with offensive odour are not produced in mfr.. The modified polyamide-<u>polyamines</u> have highly reactive <u>amino</u> and mercapto gps. and excellent rapid and low temp. epoxy resin curative properties. Cured epoxy resins have improved corrosion resistance and excellent chemical, water and alkali resistance.

CHOSEN-DRAWING: Dwg.0/2

TITLE-TERMS: MANUFACTURE MODIFIED POLYAMIDE POLY <u>AMINE</u> CURE PROPERTIES COMPRISE REACT <u>THIIRANE</u> COMPOUND POLYAMIDE POLY <u>AMINE</u> FORMATION BY=PRODUCT SULPHUR COMPOUND

DERWENT-CLASS: A21 A23 A97 H07

CPI-CODES: A02-B; A05-A01B1; A05-F04; A08-A06; A08-A07; A08-C08; A08-D03; A08-D04; A10-E01; A12-W02A; H07-G;

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L7: Entry 21 of 144

File: JPAB

Jul 11, 1995

PUB-NO: JP407173283A

DOCUMENT-IDENTIFIER: JP 07173283 A

TITLE: PRODUCTION OF MODIFIED POLYAMIDE-POLYAMINE

PUBN-DATE: July 11, 1995

INVENTOR-INFORMATION:

NAME

COUNTRY

KIMURA, KAZUMASA

KAI, TAKASHI

ASSIGNEE-INFORMATION:

NAME

COUNTRY

NIPPON SHOKUBAI CO LTD

APPL-NO: JP05317979

APPL-DATE: December 17, 1993

INT-CL (IPC): C08 G 73/02; C08 G 69/48; C07 D 331/02

ABSTRACT:

PURPOSE: To obtain a modified polyamide-polyamine having highly reactive <u>amino</u> and mercapto groups in the molecule and used as a curing agent for epoxy resin by reacting a polyamide-polyamine with a specified <u>thiirane</u> compound.

CONSTITUTION: A polyamide-polyamine compound is reacted with a <u>thiirane</u> compound of the formula (wherein R1, R2, R3 and R3 may be the same or different and are each H, alkyl or an aromatic group). Examples of the <u>thiirane</u> compound include ethylene sulfide, propylene sulfide, butylene sulfide and styrene sulfide. The polyamide-polyamine compound is obtained by the condensation of a polycarboxylic acid compound and a <u>polyamine</u> compound, an example thereof being a product of condensation of a polymeric fatty acid, such as a dimer or trimer acid, obtained by polymerizing a fatty acid having unsaturated bonds in the molecule with a <u>polyamine</u> compound, especially an aliphatic polyamine.

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